



Description

The A150N50X4A is high performance Aluminum Nitride (AlN) chip termination intended as a cost competitive alternative to Beryllium Oxide (BeO). The termination is well suited to all cellular frequency bands such as; AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating circulators, and for use in power combiners. The termination is also RoHS compliant!

General Specifications

Resistive Element	Thick film
Substrate	AlN Ceramic
Terminal Finish	Matte Tin over Nickel Barrier
Operating Temperature	-55 to +150°C (see de rating chart)

Tolerance is ± 0.010 ", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

Features:

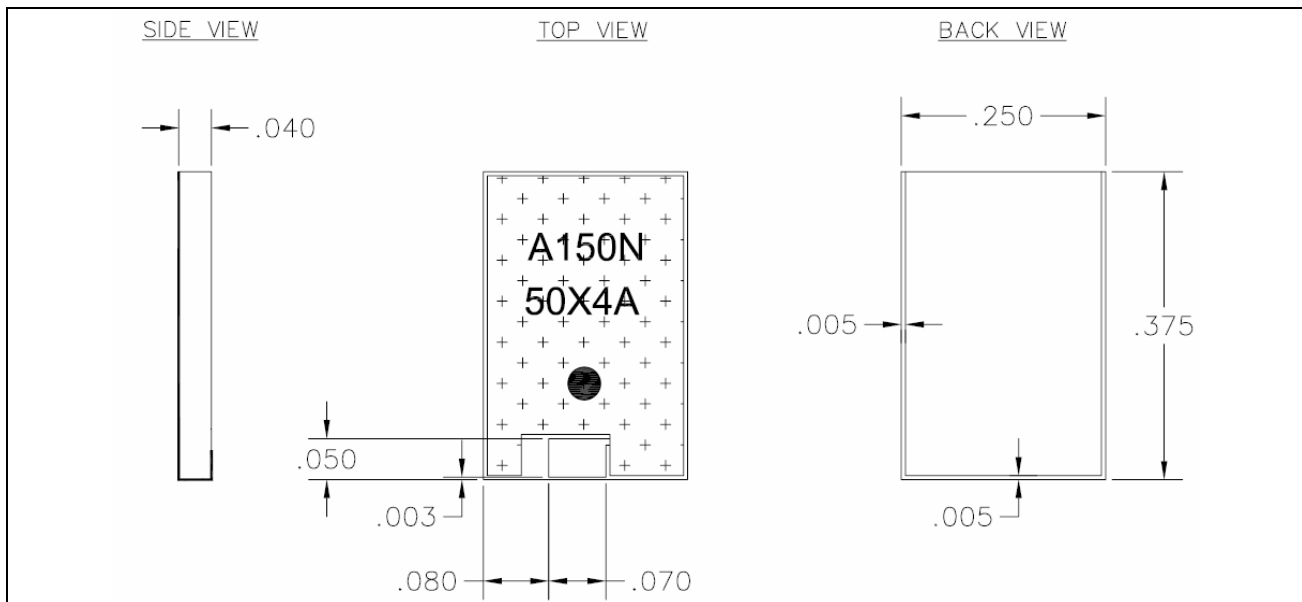
- RoHS Compliant
- 150 Watts
- DC - 2.7 GHz
- AlN Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

Electrical Specifications

Resistance Value:	50 Ohms, $\pm 2\%$
Power:	150 Watts
Frequency Range:	DC – 2.7 GHz
Return Loss	>25dB to 2 GHz >17dB to 2.7 GHz

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change.**

Outline Drawing

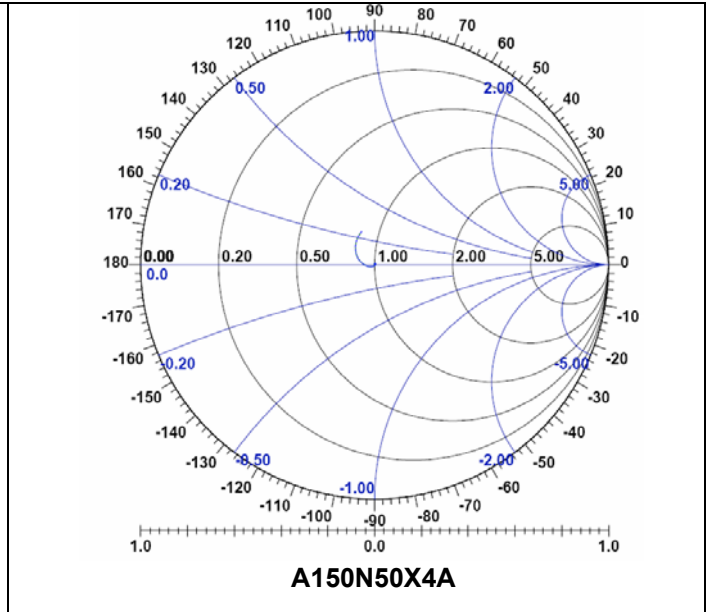
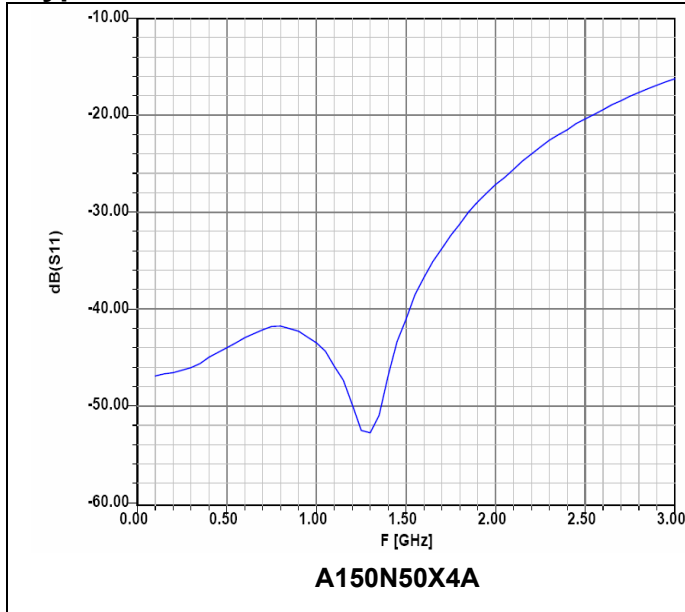


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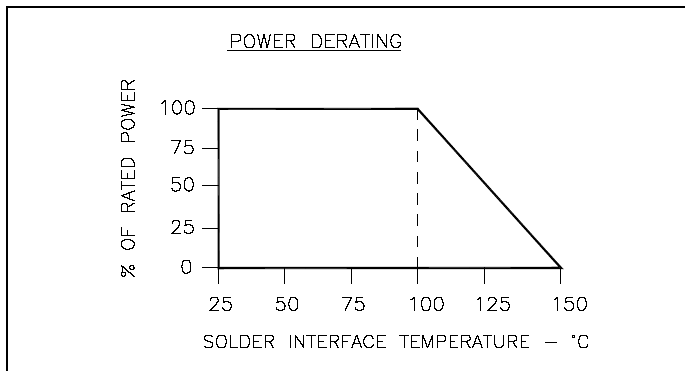




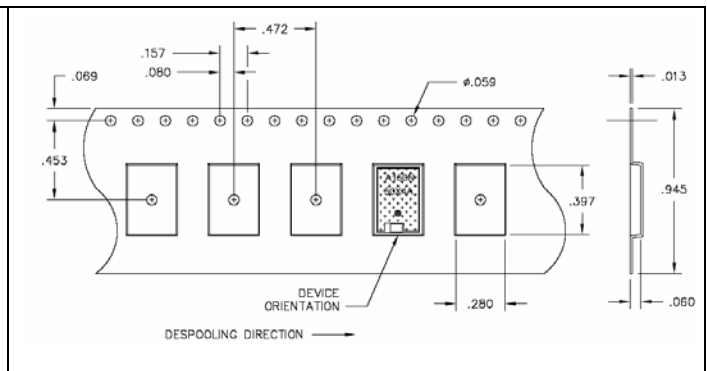
Typical Performance:



Power De-rating:



Tape & Reel:



Mounting Footprint and Procedure:

SUGGESTED STRESS RELIEF METHODS
SCALE: NONE

NOT RECOMMENDED APPLICATION
SCALE: NONE

Correct Lead Orientation

**Alternate Lead Orientation
(May Require External Matching)**

SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. POSITION DEVICE ON MOUNTING SURFACE AND SOLDER IN PLACE USING SN96 SOLDER.
3. SOLDER LEADS IN PLACE USING AN SN96 TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON (260°C).

